

**DECLARATION FOR PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe that, I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled THREE-DIMENSIONAL STACKED SEMICONDUCTOR PACKAGE DEVICE WITH BENT AND FLAT LEADS, the specification of which is identified as Attorney Docket No. BDG005-6 and attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to patentability in accordance with 37 C.F.R. §§ 1.56(a)-(b) as set forth on the attached sheet at Page 3 hereof and which I have read.

I hereby claim foreign priority benefits under 35 U.S.C. §§ 119(a)-(d) or 365(a)-(b) of any foreign application(s) for patent or inventor's certificate(s) or PCT international application(s) which designate at least one country other than the United States of America, listed below and have also identified below any foreign application(s) for patent or inventor's certificate(s) or PCT international application(s) having a filing date before that of the application(s) on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
<u>Number</u>	<u>Country</u>	<u>Month/Day/Year Filed</u>	<u>Yes</u>	<u>No</u>
N/A				

I hereby claim the benefit under 35 U.S.C. §§ 120 and 365(c) of any United States application(s) and any PCT international application(s) designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in such prior application(s) in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information material to patentability in accordance with 37 CFR §§ 1.56(a)-(b) which occurred between the filing date(s) of the prior application(s) and the national or PCT international filing date of this application:

<u>Application Serial No.</u>	<u>Filing Date</u>	<u>Status: patented, pending, abandoned</u>
10/137,494	April 30, 2002	Pending
10/136,954	April 30, 2002	Pending
10/042,812	January 9, 2002	Pending

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

<u>Application Serial No.</u>	<u>Filing Date</u>
N/A	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1) Inventor's Signature Cheng-Lien Chiang Date Oct. 23, 03'
Inventor's Name (typed): Cheng-Lien Chiang

Citizenship: Taiwan

Residence: 4th Floor, #98, Lane 85, Lin-Sen North Road
Taipei, Taiwan 104

Post Office Address: Same as Residence

37 C.F.R. §§ 1.56(a)-(b)
DUTY TO DISCLOSE INFORMATION MATERIAL
TO PATENTABILITY

(a) A patent by its very nature is affected with a public interest. The public interest is best served, and the most effective patent examination occurs when, at the time an application is being examined, the Office is aware of and evaluates the teachings of all information material to patentability.

Each individual associated with the filing and prosecution of a patent application has a duty of candor and good faith in dealing with the Office, which includes a duty to disclose to the Office all information known to that individual to be material to patentability as defined in this section. The duty to disclose information exists with respect to each pending claim until the claim is cancelled or withdrawn from consideration, or the application becomes abandoned. Information material to the patentability of a claim that is cancelled or withdrawn from consideration need not be submitted if the information is not material to the patentability of any claim remaining under consideration in the application. There is no duty to submit information which is not material to the patentability of any existing claim. The duty to disclose all information known to be material to patentability is deemed to be satisfied if all information known to be material to patentability of any claim issued in a patent was cited by the Office or submitted to the Office in the manner prescribed by §§1.97(b)-(d) and 1.98. However, no patent will be granted on an application in connection with which fraud on the Office was practiced or attempted or the duty of disclosure was violated through bad faith or intentional misconduct. The Office encourages applicants to carefully examine:

(1) prior art cited in search reports of a foreign patent office in a counterpart application,
and

(2) the closest information over which individuals associated with the filing or prosecution of a patent application believe any pending claim patentably defines, to make sure that any material information contained therein is disclosed to the Office.

(b) Under this section, information is material to patentability when it is not cumulative to information already of record or being made of record in the application, and

(1) It establishes, by itself or in combination with other information, a prima facie case of unpatentability of a claim; or

(2) It refutes, or is inconsistent with, a position the applicant takes in:

(i) Opposing an argument of unpatentability relied on by the Office, or

(ii) Asserting an argument of a patentability.

A prima facie case of unpatentability is established when the information compels a conclusion that a claim is unpatentable under the preponderance of evidence, burden-of-proof standard, giving each term in the claim its broadest reasonable construction consistent with the specification, and before any consideration is given to evidence which may be submitted in an attempt to establish a contrary conclusion of patentability.*

*Note, 37 C.F.R. § 1.97(h) states: "The filing of an information disclosure statement shall not be construed to be an admission that the information cited in the statement is, or is considered to be, material to patentability as defined in §1.56(b)."

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR
PACKAGE DEVICE WITH BENT AND FLAT LEADS
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: BDG005-6


COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

POWER OF ATTORNEY

Bridge Semiconductor Corporation, as assignee of the entire interest in the above-identified application, hereby appoints the following attorney to prosecute this application and to transact all business in the United States Patent and Trademark Office in connection therewith.

David M. Sigmond
Reg. No. 34,013

Attached to this power is a Statement Under 37 C.F.R. § 3.73(b) Establishing Right of Assignee to Take Action.

By: 
Charles W.C. Lin
Chief Executive Officer
Bridge Semiconductor Corporation

Date: Oct 23, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Cheng-Lien Chiang		
Assignee:	Bridge Semiconductor Corporation		
Title:	THREE-DIMENSIONAL STACKED SEMICONDUCTOR PACKAGE DEVICE WITH BENT AND FLAT LEADS		
Serial No.:	Unknown	Filed:	Herewith
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**STATEMENT CLAIMING SMALL ENTITY STATUS
BY SMALL BUSINESS CONCERN**

I hereby state that I am an official of the small business concern empowered to act on behalf of the concern identified below:

Bridge Semiconductor Corporation
3rd Floor, 157 Li-Te Road
Peitou District
Taipei, Taiwan 112

I hereby state that the above-identified small business concern qualifies as a small business concern, as defined in 13 C.F.R. § 121.12, and reproduced in 37 C.F.R. § 1.9(d), for purposes of paying reduced fees to the United States Patent and Trademark Office under Sections 41(a) and 41(b) of Title 35 of the United States Code in that the number of employees of the concern, including those of its affiliates, does not exceed 500 persons. For purposes of this Statement, (1) the number of employees of the business concern is the average over the previous fiscal year of the concern of the persons employed on a full-time, part-time or temporary basis during each of the pay periods of the fiscal year, and (2) concerns are affiliates of each other

when either, directly or indirectly, one concern controls or has the power to control the other, or a third party controls or has the power to control both.

I hereby state that rights under contract or law have been conveyed to, and remain with, the small business concern identified above with regard to the invention described in the specification filed herewith with the title as listed above.

If the rights held by the above-identified small business concern are not exclusive, each individual, concern or organization having rights in the invention is listed below and no rights to the invention are held by any person, other than the inventor, who would not qualify as an independent inventor under 37 C.F.R. § 1.9(c) if that person had made the invention, or by any concern that would not qualify as a small business concern under 37 C.F.R. § 1.9(d), or a nonprofit organization under 37 C.F.R. § 1.9(e).

Each such person, concern, or organization having any rights in the invention is listed below:

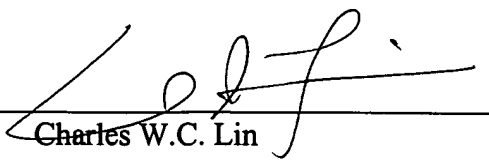
➤ No such person, concern or organization exists.

I acknowledge that separate statements are required from each named person, concern or organization having rights to the invention stating their status as small entities in accordance with 37 C.F.R. § 1.27.

I acknowledge the duty to file, in this application or patent, notification or any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate in accordance with 37 C.F.R. § 1.28(b).

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application, any patent issued thereon, or any patent to which this verified statement is directed.

By:



Charles W.C. Lin

Chief Executive Officer

Bridge Semiconductor Corporation

3rd Floor, 157 Li-Te Road

Peitou District

Taipei, Taiwan 112

Date: Oct 23, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

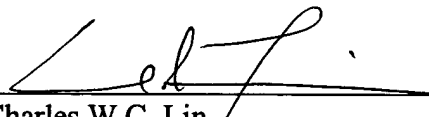
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**STATEMENT UNDER 37 C.F.R. § 3.73(B)
ESTABLISHING RIGHT OF ASSIGNEE TO TAKE ACTION**

Bridge Semiconductor Corporation is the assignee of the entire interest in the above-identified application by virtue of an Assignment from the inventor of the above-identified application. The Assignment is submitted herewith for recordal in the Patent and Trademark Office. A copy of the Assignment is attached.

The assignee seeks to take action in the Patent and Trademark Office in this matter. The undersigned is empowered to sign this Statement on behalf of the assignee.

By: 
Charles W.C. Lin
Chief Executive Officer
Bridge Semiconductor Corporation

Date: Oct. 23, 2003